

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>				
<b>Filing Date:</b>				
<b>Title of Invention:</b>	MULTILAYER SUBSTRATE WITH BUILT-IN CHIP-TYPE ELECTRONIC COMPONENT AND METHOD FOR MANUFACTURING THE SAME			
<b>First Named Inventor:</b>	Osamu CHIKAGAWA			
<b>Filer:</b>	Stephen Russell Funk/Allison Cowan			
<b>Attorney Docket Number:</b>	36856.1458			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
National Stage Fee	1631	1	300	300
Natl Stage Search Fee - Report provided	1642	1	400	400
National Stage Exam - all other cases	1633	1	200	200
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				900